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cont

is an exposed surface of silicon, and wherein an adhesion strength between said rear surface of said semiconductor chip and said resin material of said resin body is relatively greater than an adhesion strength between a material of said die pad of said lead frame and said resin material of said resin body.

B³

31. (Amended) A semiconductor device according to claim 30, wherein an adhesion strength between a material of said organic film and a resin material of said resin body is relatively greater than an adhesion strength between a material of said inorganic film and said resin material of said resin body.

B⁴

33. (Amended) A semiconductor device according to claim 32, wherein said semiconductor chip is a silicon chip and said rear surface of said semiconductor chip is an exposed surface of silicon, and wherein an adhesion strength between said rear surface of said semiconductor chip and said resin material of said resin body is relatively greater than an adhesion strength between a material of said die pad of said lead frame and said resin material of said resin body.
